

ON Semiconductor				10/15/2019
Base Part		KA324		Pb-free
Orderable Part		KA324	Total weight (mg)	1042.694
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	0.905	Silicon (Si)	7440-21-3	100
Die Attach	0.099	Silver (Ag)	7440-22-4	75
		Phenolic Resin-2	54208-63-8	25
Lead Frame	327.672	Silver (Ag)	7440-22-4	0.5005005
		Zinc (Zn)	7440-66-6	0.12024219
		Iron (Fe)	7439-89-6	2.30108157
		Copper (Cu)	7440-50-8	97.04826778
		Phosphorus (P)	7723-14-0	0.02990796
Mold Compound-Black	691.07	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8	0.99989871
		Ortho Cresol Novolac Resin	29690-82-2	28.50651888
		Antimony Trioxide (Sb2O3)	1309-64-4	2.99535503
		Carbon Black (C)	1333-86-4	0.50067287
		Fused Silica (SiO2)	60676-86-0	66.99755452
Plating	22.6	Tin (Sn)	7440-31-5	100
Wire Bond - Au	0.348	Gold (Au)	7440-57-5	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				